

In the Claims:

Please cancel claims 1-47.

Following is a complete listing of the claims pending in the application, as amended:

1-47. (Cancelled)

48. (Original) A process of electrically coupling a microelectronic component to a substrate, comprising:

forming a plurality of multi-layer bond pads by:

depositing an intermediate bond layer of a first metal on an outer surface of each of a plurality of integrated bond pads carried by an active surface of the microelectronic component, the integrated bond pads being formed of a metal different from the first metal; and

thereafter, depositing an outer bond layer on the intermediate bond layer deposited on each integrated bond pad, the outer bond layer comprising a second metal which is different from the first metal;

thereafter, positioning the microelectronic component with respect to the substrate with the active surface of the microelectronic component spaced from a contact surface of the substrate;

ball bonding a first end of a first bonding wire to a first contact carried by the contact surface of the substrate, the first bonding wire comprising the first metal; and

stitch bonding a second end of the first bonding wire to the outer bond layer of a first one of the multi-layer bond pads.

49. (Original) The method of claim 48 wherein the first metal comprises gold.

50. (Original) The method of claim 48 wherein the outer bond layer is electrodeposited.

51. (Original) The method of claim 48 further comprising ball bonding a first end of a second bonding wire to a second contact carried by the contact surface and stitch bonding a second end of the second bonding wire to the outer bond layer of a second one of the multi-layer bond pads.